

IN THE CLAIMS:

1 1. (Original) A wire loop comprising:

2 a wire connecting a first bonding point and a second bonding point therethrough;

3 said wire including a ball bonded to said first bonding point, a neck portion
4 adjacent to said ball and a major portion extending from said neck portion to said second
5 bonding point;

6 wherein said major portion of said wire has a crushed part formed in proximity to
7 said neck portion by crushing the part of said wire together with a top portion of said ball.

1 2. (Original) The wire loop as defined in claim 1, wherein said neck portion

2 includes a first kink formed by a part of said neck portion being doubled over.

1 3. (Original) The wire loop as defined in claim 1, wherein said major portion of said

2 wire includes a horizontal portion extending in a substantially horizontal direction from said
3 neck portion and an inclined portion which extends from said horizontal portion to said second
4 bonding point and which has an end thereof bonded to said second bonding point; and

5 said inclined portion is connected to said horizontal portion through a second kink
6 formed in a part of said wire therebetween.

1 4. (Original) The wire loop as defined in claim 2, wherein said major portion of said

2 wire includes a horizontal portion extending in a substantially horizontal direction from said
3 neck portion and an inclined portion which extends from said horizontal portion to said second
4 bonding point and which has an end thereof bonded to said second bonding point; and

5 said inclined portion is connected to said horizontal portion through a second kink
6 formed in a part of said wire therebetween.

1 5. (Original) The wire loop as defined in claim 2, wherein said neck portion
2 includes at least one additional doubled over kink like said first kink.

1 6-13. (Cancelled)

1 14. (Original) A semiconductor device comprising:
2 a first bonding point;
3 a second bonding point; and
4 a wire bonded to said first bonding point and said second bonding point to
5 connect said first bonding point and said second bonding point therethrough;
6 wherein said wire includes a ball bonded to said first bonding point, a neck
7 portion adjacent to said ball and a major portion extending from said neck portion to said second
8 bonding point; and
9 wherein said major portion of said wire has a crushed part formed in proximity to
10 said neck portion by crushing the part of said wire together with a top portion of said ball.

1 15. (Original) The semiconductor device as defined in claim 14, wherein said neck
2 portion includes a first kink formed by a part of said neck portion being doubled over.

1 16. (Original) The semiconductor device as defined in claim 15, wherein said neck
2 portion includes at least one additional doubled over kink like said first kink.

1 17. (New) An improved wire loop connector for electrical connection between a
2 semiconductor device and a lead frame comprising:

3 a wire body of a predetermined length;

4 a first end of the wire body for electrical connection with the semiconductor
5 device having an immediately adjacent first overlaid length of the wire body to double the
6 overall thickness of the wire body at the electrical connection; and

7 a second distal end of the wire body for electrical connection with the lead frame
8 having a thickness of the wire body wherein the height of the wire body relative to a distance
9 above the semiconductor device is restricted.

1 18. (New) The improved wire loop connection of Claim 17 further including at the
2 first end of the wire body a second overlaid length of the wire body wherein a thickness is
3 quadruple the overall thickness of the wire body.

1 19. (New) The improved wire loop connection of Claim 18 wherein the wire body
2 has been bent three times to integrally form the quadruple overall thickness with each bent length
3 closed upon another length of the wire body.